Datasheet

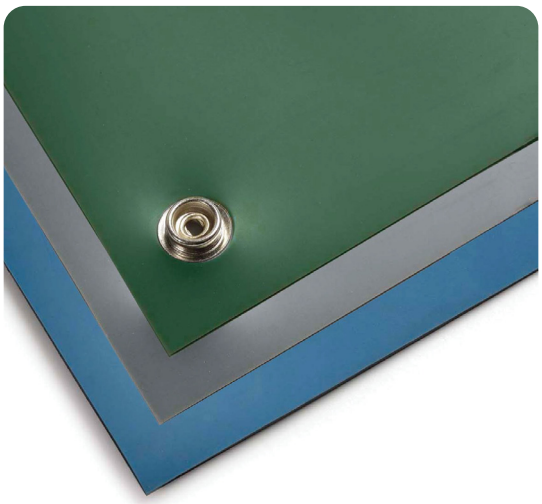
ENGLISH

ESD Bench Matting – 2 & 3 Layer, Smooth Finish

FEATURES:

Anti-static matting should be laid out in the workshops or advanced laboratories for microelectronic industries such as electronic semi-conduct devices, electronic computers, electronic communication equipment and integrated circuits etc.

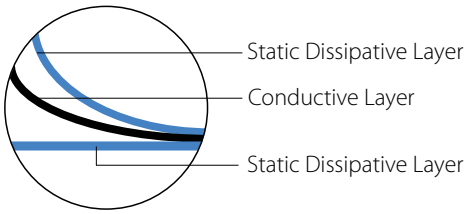
- Great value ESD Bench Matting made from anti-static (conductive) and static-dissipative materials with synthetic rubber
- All bench mats come with 10mm studs in each corner



3 LAYER

- 3mm thick double-layer structure
- Surface layer is a 1.25mm thick static-dissipative layer
- Middle layer is a 0.5mm conductive layer
- Bottom layer is a 1.25mm thick static-dissipative layer

3 LAYER CONSTRUCTION:



CONFORMS TO ESD S20.20 AND EN 61340-5-1 ESD.

TEST RESULTS:

	TEST METHOD:	UNIT:	VALUE:
Surface Resistance / R_{TG}	SJ/T10694-2004	Ω	$1x10^6 \leq R \leq 1x10^9$
Bottom Resistance / R_{TT}	SJ/T10694-2004	Ω	$1x10^3 \leq R \leq 1x10^6$
Volume Resistance	GB/T14437-97	Ω	$1x10^5 \leq R \leq 1x10^8$
Thickness	YY-1001	mm	Permissable Tolerance +0.1
Temperature Resistance	YY-1001	°C	180 (Instantaneous Temp)
Temperature	N/A	°C	20-26
Relative Humidity	N/A	%	40-65

R_{TG} is the resistance from one point on the mat's surface to the mat's ground point, and is the fundamental electrical test for a mat. A proper R_{TG} insures that a mat can conduct charge from a point on the surface to the mat ground point. The guideline in ESD STM-4.1 for R_{TG} is $1x10^6$ to $1x10^9$ Ω. ANSI/ESD S-20.20 has an upper limit of $<1 x10^9$ Ω. R_{TT} is the resistance from one point on the mat's surface to another point. A proper R_{TT} insures the consistency of the mat's resistance properties. The ESD STM-4.1 guideline for R_{TT} is $>1x10^6$ Ω.

ARTICLE:	DESCRIPTION:	SIZE:	ADDITIONAL NOTES:
7872102	Buried Layer Matting	1200x600x3mm	Blue